

FFSB0865B

Silicon Carbide Schottky Diode

650 V, 8 A

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 33 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Peak Repetitive Reverse Voltage		V_{RRM}	650	V
Single Pulse Avalanche Energy ($T_J = 25^{\circ}\text{C}$, $I_{L(pk)} = 11.5\text{ A}$, $L = 0.5\text{ mH}$, $V = 50\text{ V}$)		E_{AS}	33	mJ
Continuous Rectified Forward Current	@ $T_C < 147$	I_F	8.0	A
	@ $T_C < 135$		10.1	
Non-Repetitive Peak Forward Surge Current	$T_C = 25^{\circ}\text{C}$ $t_p = 10\text{ }\mu\text{s}$	I_{FM}	577	A
	$T_C = 150^{\circ}\text{C}$ $t_p = 10\text{ }\mu\text{s}$		533	
Non-Repetitive Forward Surge Current (Half-Sine Pulse)	$T_C = 25^{\circ}\text{C}$ $t_p = 8.3\text{ ms}$	I_{FSM}	56	A
Power Dissipation	$T_C = 25^{\circ}\text{C}$	P_{tot}	73	W
	$T_C = 150^{\circ}\text{C}$		12	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +175	$^{\circ}\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

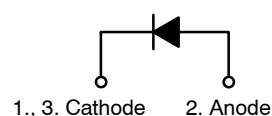
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{\theta JC}$	2.05	$^\circ\text{C/W}$



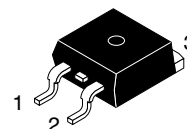
ON Semiconductor®

www.onsemi.com

V_{RRM}	I_F
650 V	8.0 A

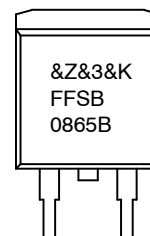


Schottky Diode



D²PAK-3
TO-263
CASE 418BK

MARKING DIAGRAM



&Z = Assembly Plant Code
&3 = Numeric Date Code
&K = Lot Code
FFSB0865B = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FFSB0865B

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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ON CHARACTERISTICS

Forward Voltage	V _F	I _F = 8.0 A, T _J = 25°C		1.39	1.7	V
		I _F = 8.0 A, T _J = 125°C		1.55	2.0	
		I _F = 8.0 A, T _J = 175°C		1.71	2.4	
Reverse Current	I _R	V _R = 650 V, T _J = 25°C		0.5	40	μA
		V _R = 650 V, T _J = 125°C		1.0	80	
		V _R = 650 V, T _J = 175°C		2.0	160	

CHARGES, CAPACITANCES & GATE RESISTANCE

Total Capacitive Charge	Q _C	V _C = 400 V		22		nC
	C _{tot}	V _R = 1 V, f = 100 kHz		336		pF
		V _R = 200 V, f = 100 kHz		39		
		V _R = 400 V, f = 100 kHz		30		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FFSB0865B	FFSB0865B	D ² PAK	Tape & Reel†	330 mm	24 mm	800 Units

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

TYPICAL CHARACTERISTICS

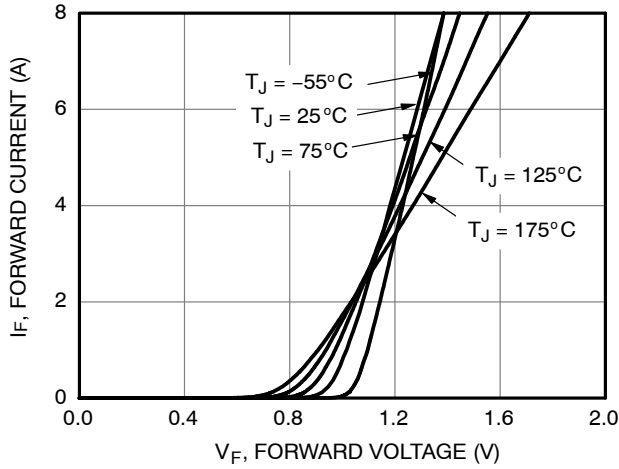


Figure 1. Forward Characteristics

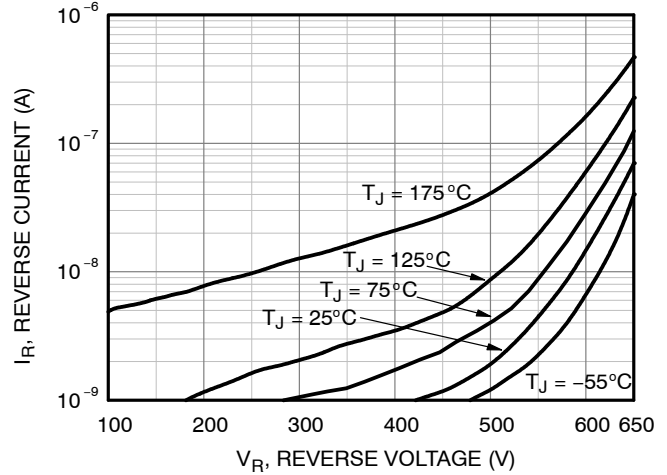


Figure 2. Reverse Characteristics

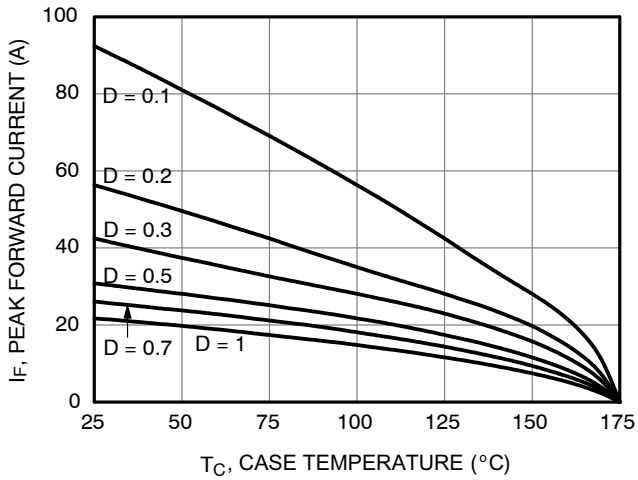


Figure 3. Current Derating

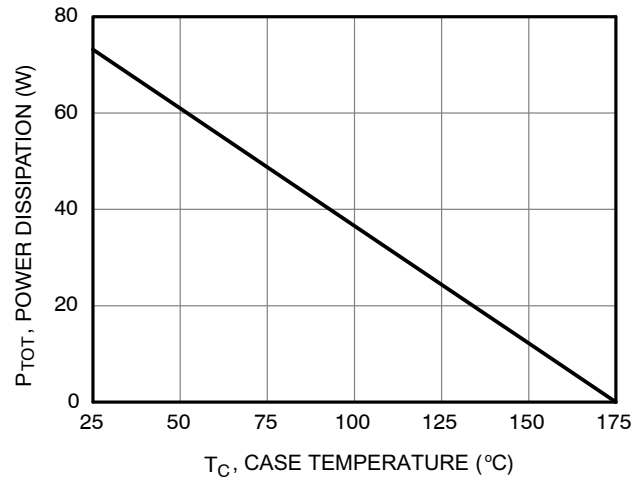


Figure 4. Power Derating

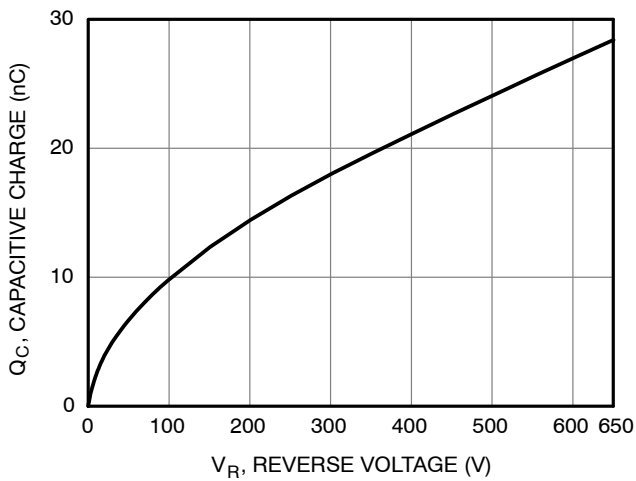


Figure 5. Capacitive Charge vs. Reverse Voltage

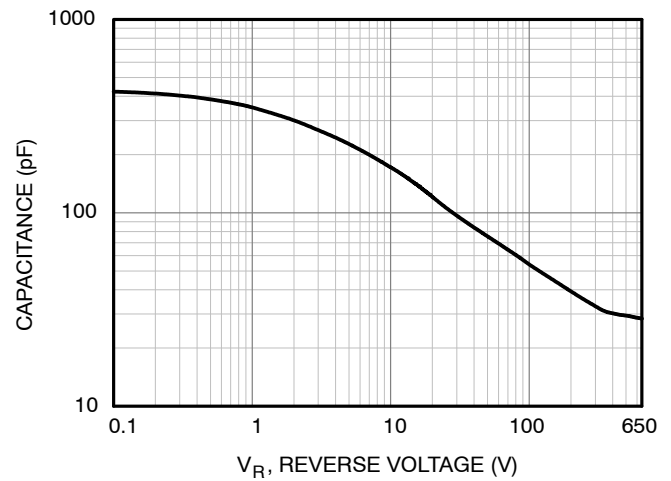


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

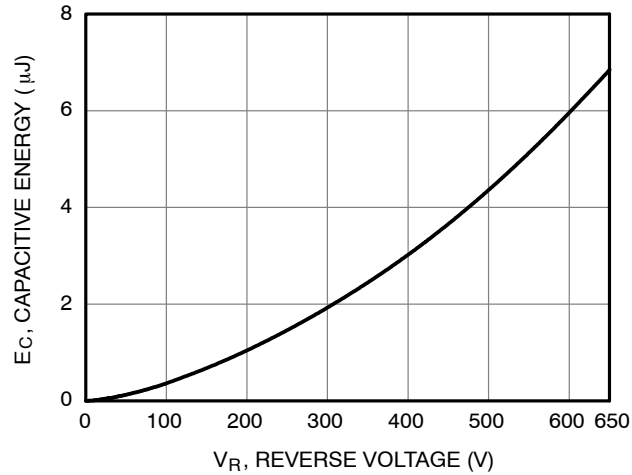


Figure 7. Capacitance Stored Energy

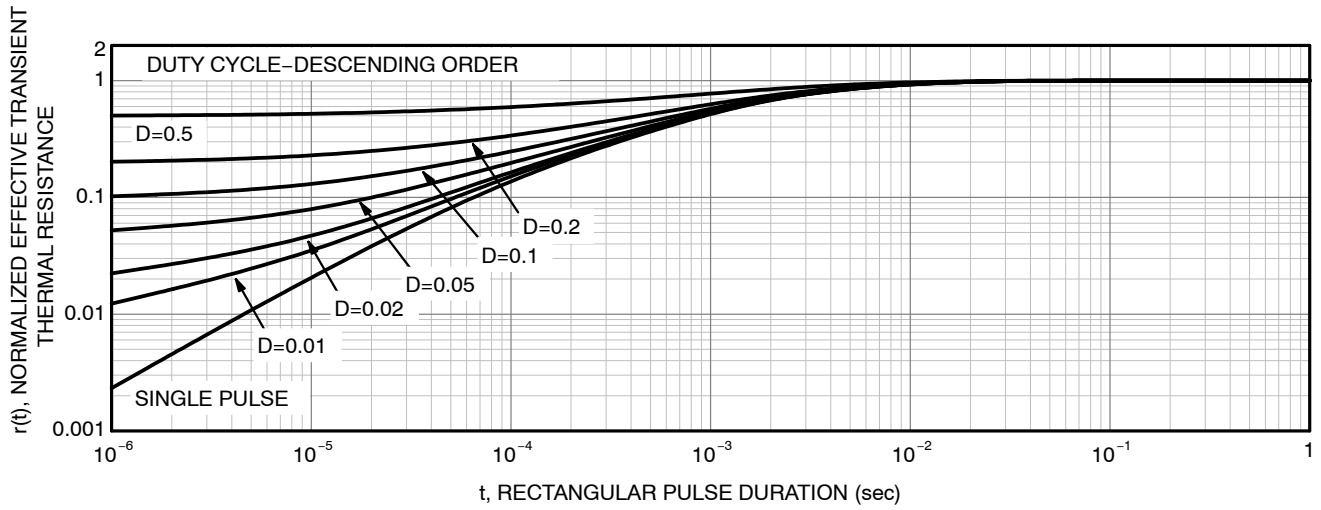


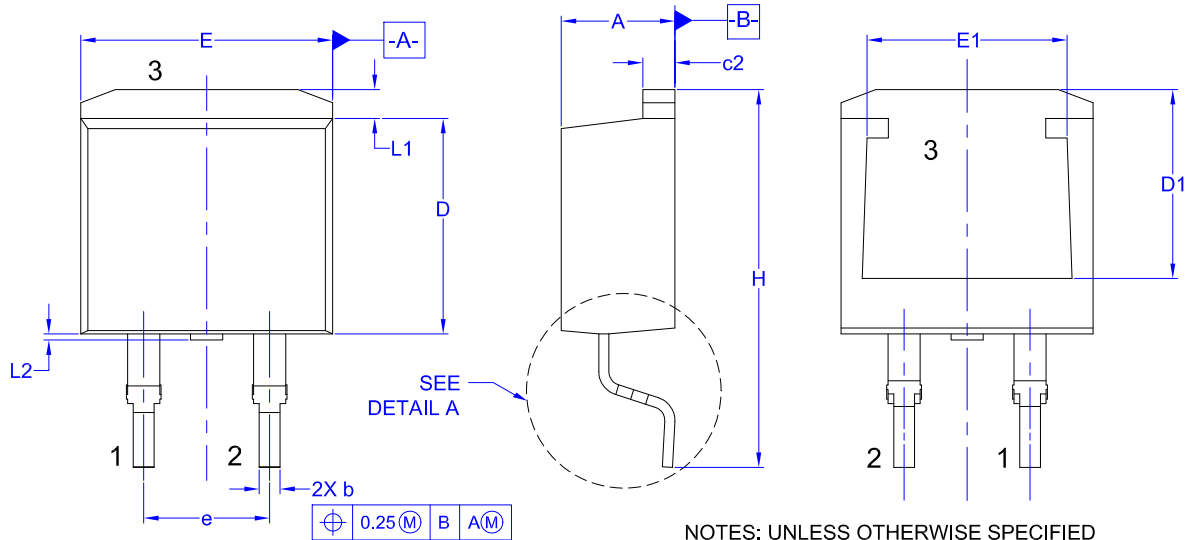
Figure 8. Junction-to-Case Transient Thermal Response

PACKAGE DIMENSIONS

D²PAK2 (TO-263-2L)

CASE 418BK

ISSUE O



NOTES: UNLESS OTHERWISE SPECIFIED

A) ALL DIMENSIONS ARE IN MILLIMETERS.

B) REFERENCE JEDEC, TO-263, VARIATION AB.

C) DIMENSIONING AND TOLERANCING PER

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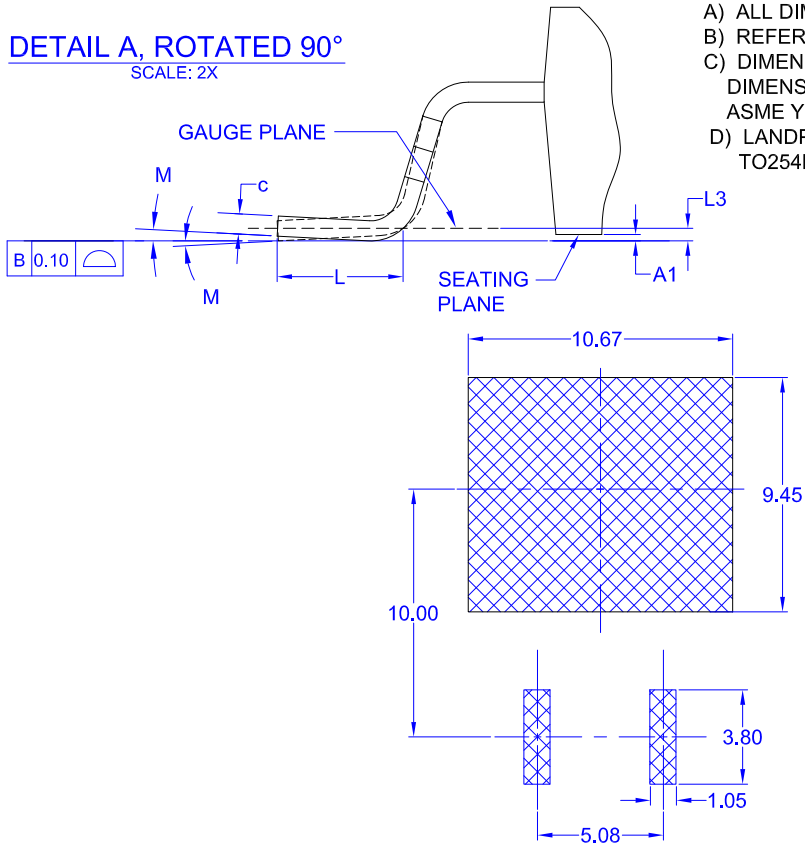
ASME Y14.5 - 2009.

D) LANDPATTERN RECOMMENDATION PER IPC

TO254P1524X482-3N

DETAIL A, ROTATED 90°

SCALE: 2X

LAND PATTERN RECOMMENDATION
UNLESS NOTED, ALL DIMS TYPICAL

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